

		Material Composition Declaration Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.						
1752-2 1.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x		Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information				
Supplier Information										
Company Name * National Semiconductor		Company Unique ID NATSEMI		Unique ID Authority 04-147-2986		Response Date * 11-11-2011		Response Document ID		
Contact Name * Lorena Dudman		Title - Contact Product Stewardship Eng.		Phone - Contact * 1-408-721-8180		Email - Contact * Green.Project@nsc.com				
Authorized Representative * Lorena Dudman		Title - Representative Product Stewardship Eng.		Phone - Representative * 1-408-721-8180		Email - Representative * Green.Project@nsc.com		Supplier Comments or URL for Additional Information http://www.national.com/analog/quality/green		
	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type	
		LM2587S-3.3	LM2587S-3.3	11-11-2011			1449.87	mg	Each	
	Alternate Recommendation				Alternate Item Comments					
Manufacturing Process Information										
Terminal Plating / Grid Array Material SnPb		Terminal Base Alloy CU Alloy		J-STD-020 MSL Rating 3		Peak Process Body Temperature 235 C		Max Time at Peak Temperature 30 seconds		Number of Reflow Cycles 4
Comments "Does not contain PFOS."										

RoHS Material Type Declaration	Declaration Type * Custom
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RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

1. National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7(a) or 7(c)-I.
2. National products do not contain and are not manufactured with ozone depleting compounds.
3. National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
4. National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
5. National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION

RoHS Declaration * 2 - Item(s) contains RoHS restricted substances per the definition above and is not under exemption	Supplier Acceptance *	Accepted
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Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration and above and choose all applicable exemptions.

7(a). Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead)

Declaration Signature

Supplier Signature	 John L Conn Vice President Quality	John L. Conn Vice President Quality
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Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name	Homogeneous Material	Weight	Unit of Measure	Level	Substance Category	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance	PPM
	Ext. LeadFinish	9.411	mg	Requester		Sn	7440-31-5		7.999	mg		850,000
				Requester		Pb	7439-92-1		1.412	mg		150,000
	Leadframe	796.170	mg	Requester		Cu	7440-50-8		794.928	mg		998,440
				Requester		Sn	7440-31-5		1.194	mg		1,500
				Requester		P	7723-14-0		0.048	mg		60
	Chip	7.440	mg	Requester		Si	7440-21-3		7.395	mg		994,000
				Requester		Al	7429-90-5		0.045	mg		6,000
	Plastic	625.040	mg	Requester		SiO2	60676-86-0		556.286	mg		890,000
				Requester		Epoxy Resin	25928-94-3		50.003	mg		80,000
				Requester		Mg(OH)2	1309-42-8		18.751	mg		30,000
	Lead Plating	6.520	mg	Requester		Ni	7440-02-0		6.520	mg		1,000,000
	Die Attach	3.031	mg	Requester		Pb	7439-92-1		2.894	mg		955,000
				Requester		Ag	7440-22-4		0.076	mg		25,000
				Requester		Sn	7440-31-5		0.061	mg		20,000
	Int. LeadFinish	1.890	mg	Requester		Ag	7440-22-4		1.890	mg		1,000,000
	Wires	0.366	mg	Requester		Au or Cu	7440-57-5		0.366	mg		1,000,000